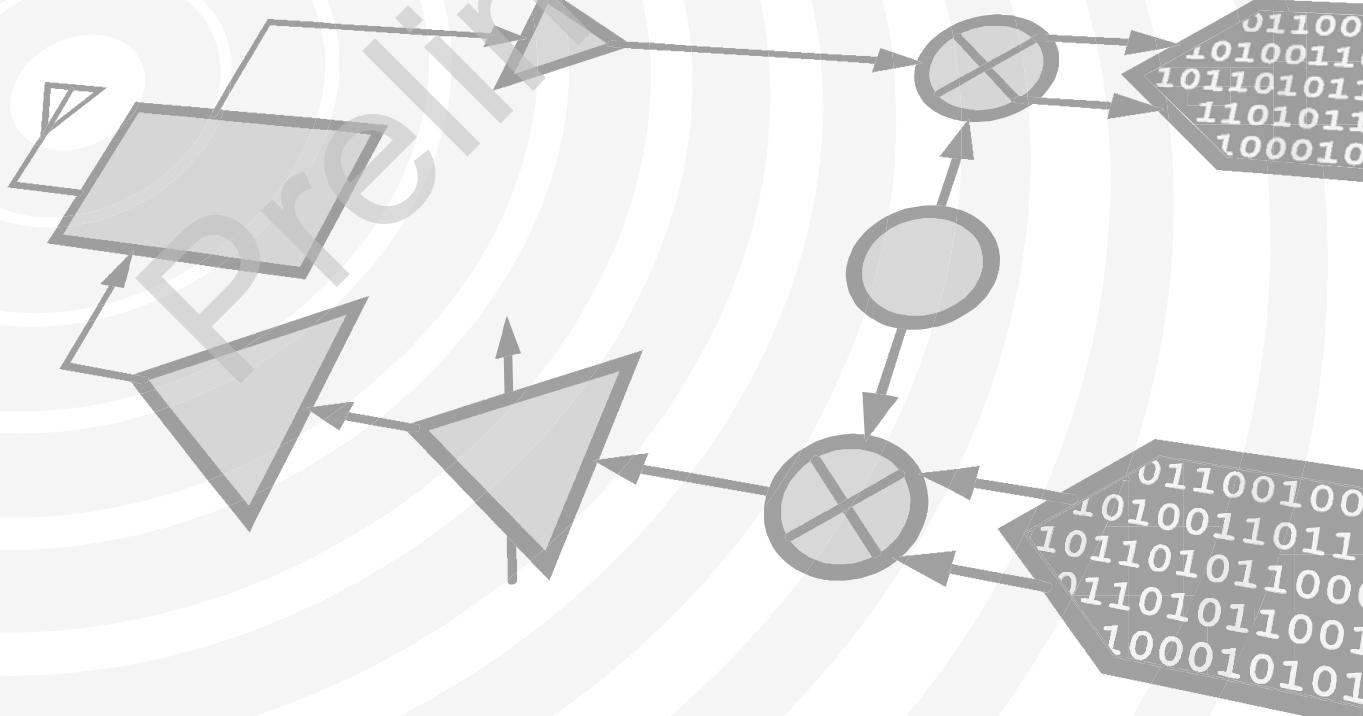


Analog Devices Welcomes Hittite Microwave Corporation



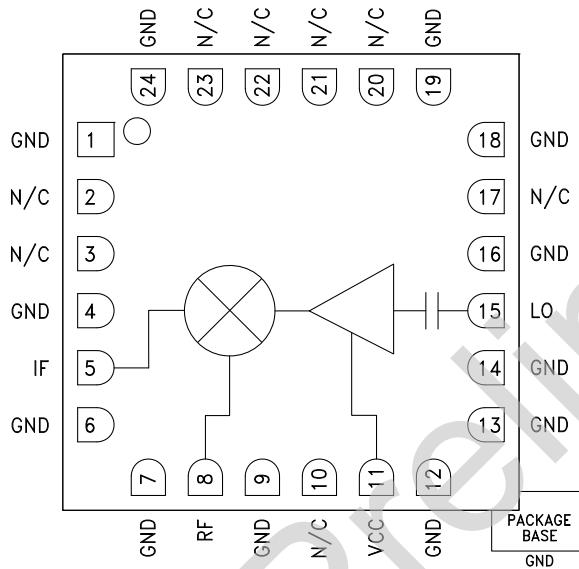
THIS PAGE INTENTIONALLY LEFT BLANK

Preliminary

**GaAs MMIC SUB-HARMONIC
SMT MIXER, 24 - 34 GHz****Typical Applications**

The HMC798ALC4 is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios & VSAT
- Test Equipment & Sensors
- Military End-Use
- SATCOM

Functional Diagram**Electrical Specifications, $T_A = +25^\circ\text{C}$, $V_{cc} = 5\text{V}$**

Parameter	IF = 1 GHz LO = 4 dBm			IF = 1 GHz LO = 4 dBm			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency Range, RF	24 - 29.5			29.5 - 34			GHz
Frequency Range, LO	12 - 16			13.5 - 17.75			GHz
Frequency Range, IF	DC - 4			DC - 4			GHz
Conversion Loss		11	13		10	12	dB
2LO to RF Isolation	25	30		20	25		dB
2LO to IF Isolation		45			35		dB
IP3 (Input)	17	20		19	22		dBm
1 dB Compression (Input)		10			12		dBm
Supply Current (Idd)		95	125		95	125	mA

*Unless otherwise noted, all measurements performed as upconverter, IF= 1 GHz, LO = 4 dBm

Absolute Maximum Ratings

RF / IF Input (Vdd = +5V)	+13 dBm
LO Drive (Vdd = +5V)	+10 dBm
Vdd	5.5V
Channel Temperature	175 °C
Continuous Pdiss (Ta = 85 °C) (derate 8.33 mW/°C above 85 °C)	0.75 mW
Thermal Resistance (junction to ground paddle)	119 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

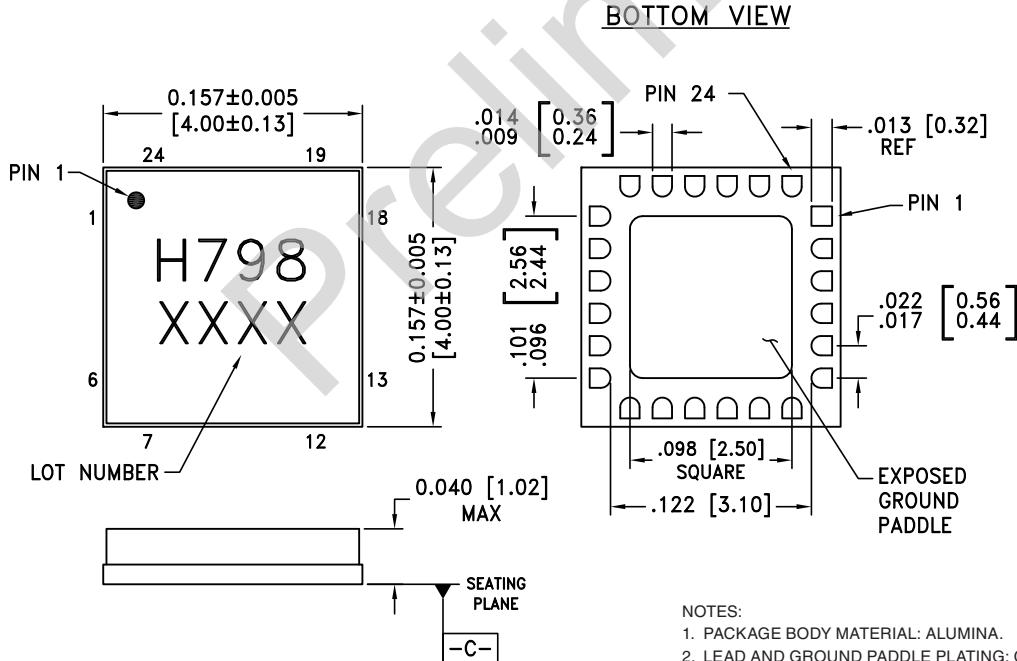
MxN Spurious Outputs

@ RF Port, Vdd = 5V

	nLO		
mIF	2	1	0
-3	68		
-2	53	71	66
-1	0	49	32
0	1	31	
1	1	45	31
2	54	66	65
3	66		

IF = 2 GHz @ -10 dBm
LO = 15 GHz @ 4 dBm
All values in dBc below IF power level (2LO - 1IF)
Measured as upconverter

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA.
2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. CHARACTERS TO BE HELVETICA MEDIUM, .025 HIGH, BLACK INK, OR LASER MARK LOCATED APPROX. AS SHOWN.
6. PACKAGE WARP SHALL NOT EXCEED 0.05MM DATUM -C-
7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.